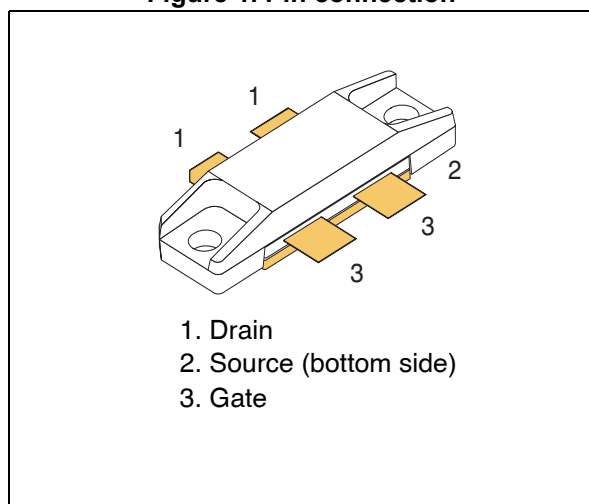


**Figure 1. Pin connection**



### Features

- Excellent thermal stability
- Common source push-pull configuration
- $P_{OUT} = 1000 \text{ W min. (1200 W typ.)}$  with 26 dB gain @ 123 MHz
- Pulse conditions: 1 msec - 10%
- In compliance with the 2002/95/EC European directive
- ST air-cavity STAC<sup>®</sup> packaging technology

### Description

The STAC4932B is an N-channel MOS field-effect RF power transistor. It is intended for 100 V pulse applications up to 250 MHz. This device is suitable for use in industrial, scientific and medical applications. The STAC4932B benefits from the latest generation of efficient, patent-pending STAC<sup>®</sup> package technology.

**Table 1. Device summary**

Order code	Marking	Package	Packaging
STAC4932B	STAC4932 <sup>(1)</sup>	STAC244B	Plastic tray

1. For more details please refer to [Chapter 6: Marking, packing and shipping specifications](#).

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# 1 Electrical data

## 1.1 Maximum ratings

Table 2. Absolute maximum ratings ( $T_{CASE} = 25\text{ °C}$ )

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}^{(1)}$	Drain source voltage	200	V
$V_{DGR}$	Drain-gate voltage ( $R_{GS} = 1\text{ M}\Omega$ )	200	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$T_J$	Max. operating junction temperature	200	°C
$T_{STG}$	Storage temperature	-65 to +150	°C

1.  $T_J = 150\text{ °C}$

## 1.2 Thermal data

Table 3. Thermal data (1 msec - 10%)

Symbol	Parameter	Value	Unit
$R_{thJC}$	Junction - case thermal resistance	0.075	°C/W

## 2 Electrical characteristics

$T_{CASE} = +25\text{ }^{\circ}\text{C}$

### 2.1 Static

Table 4. Static (per side)

Symbol	Test conditions		Min.	Typ.	Max.	Unit
$V_{(BR)DSS}^{(1)}$	$V_{GS} = 0\text{ V}$	$I_{DS} = 100\text{ mA}$	200	250		V
$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$			1	mA
$I_{GSS}$	$V_{GS} = 20\text{ V}$	$V_{DS} = 0\text{ V}$			250	nA
$V_{TH}$	$I_D = 250\text{ mA}$		2.0		4.0	V
$V_{DS(ON)}$	$V_{GS} = 10\text{ V}$	$I_D = 10\text{ A}$			3.6	V
$G_{FS}$	$V_{DS} = 10\text{ V}$	$I_D = 2.5\text{ A}$		6		S
$C_{ISS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$		570		pF
$C_{OSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$		134		pF
$C_{RSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$		8		pF

1.  $T_J = 150\text{ }^{\circ}\text{C}$

### 2.2 Dynamic

Table 5. Pulse / 1 msec - 10%

Symbol	Test conditions	Min.	Typ.	Max.	Unit
$P_{OUT}$	$V_{DD} = 100\text{ V}$ , $I_{DQ} = 2 \times 250\text{ mA}$ , $f = 123\text{ MHz}$	1000	1200	-	W
$h_D$	$V_{DD} = 100\text{ V}$ , $I_{DQ} = 2 \times 250\text{ mA}$ , $P_{OUT} = 1000\text{ W}$ , $f = 123\text{ MHz}$		60	-	%
Gain	$V_{DD} = 100\text{ V}$ , $I_{DQ} = 2 \times 250\text{ mA}$ , $P_{OUT} = 1000\text{ W}$ , $f = 123\text{ MHz}$		26	-	dB

3 Impedance

Figure 2. Current conventions

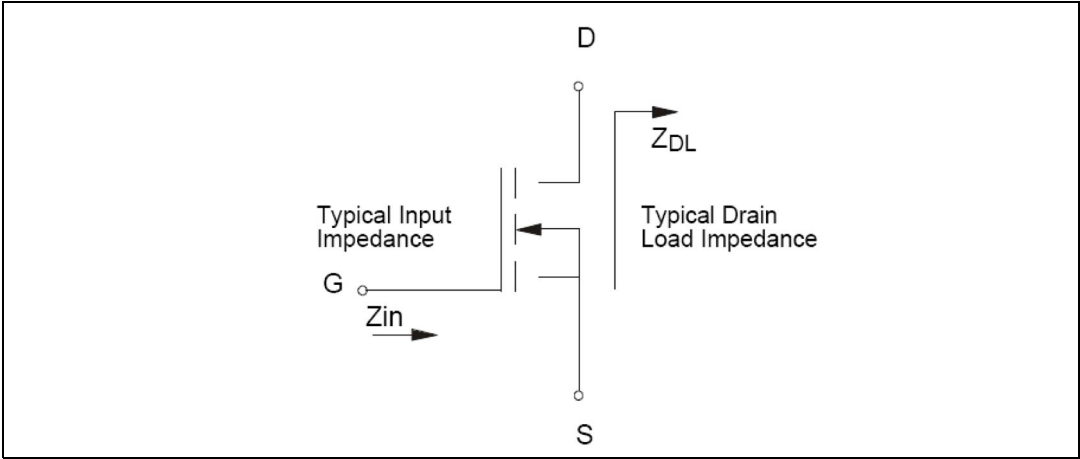


Table 6. Impedance data

Freq. (MHz)	$Z_{IN} (\Omega)$	$Z_{DL}(\Omega)$
123 MHz (pulsed)	1.3 - j 2.8	7.7 - j 9.4

Note: Measured gate-to-gate and drain-to-drain, respectively.

4 Typical performance

Figure 3. Maximum safe operating area

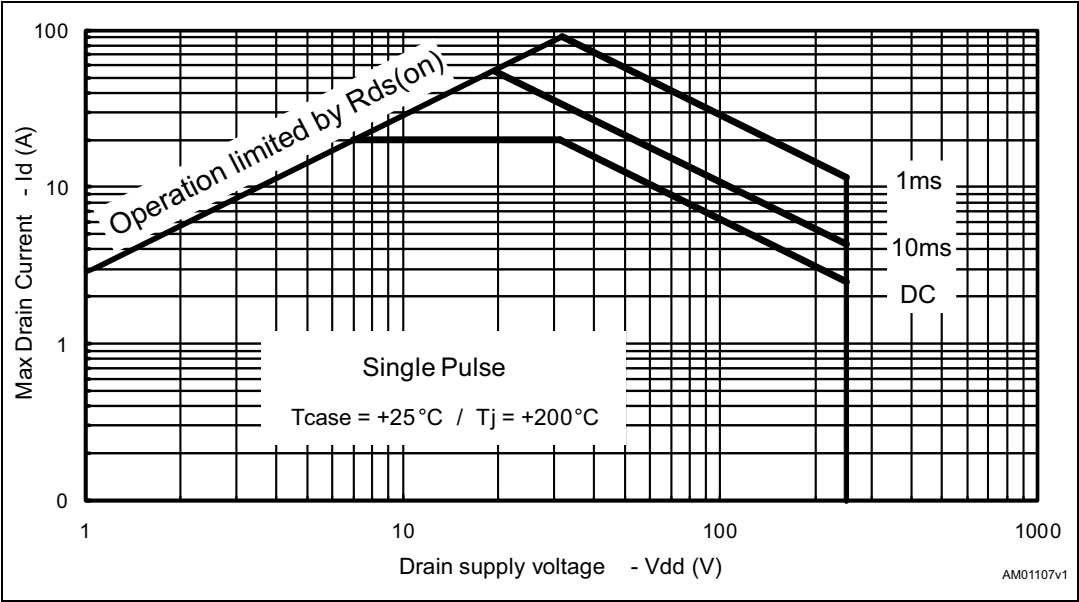


Figure 4. Transient thermal impedance

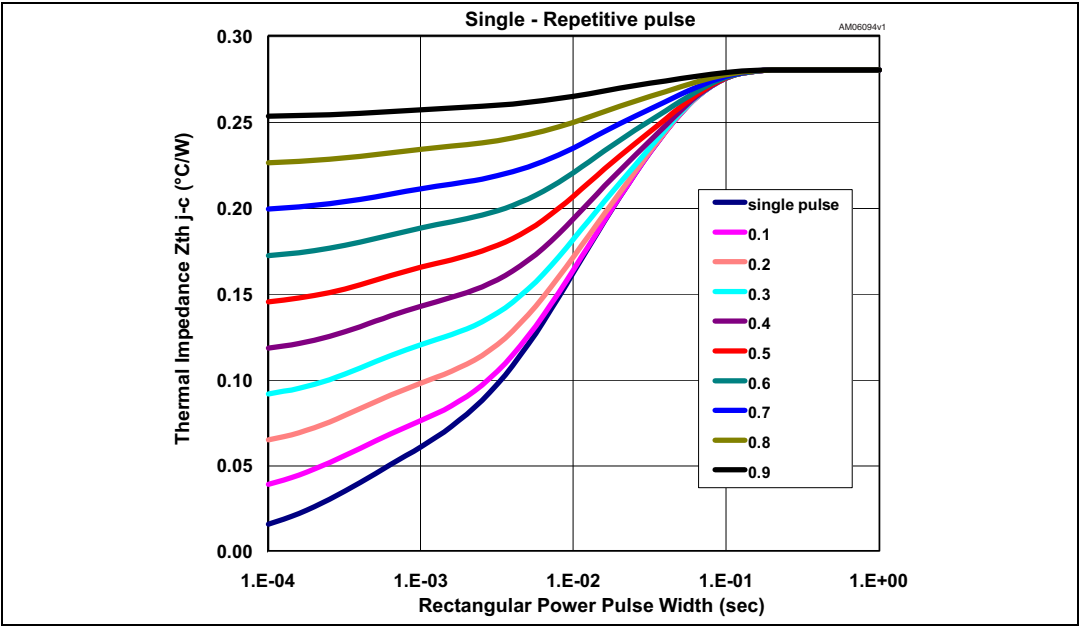


Figure 5. Transient thermal model

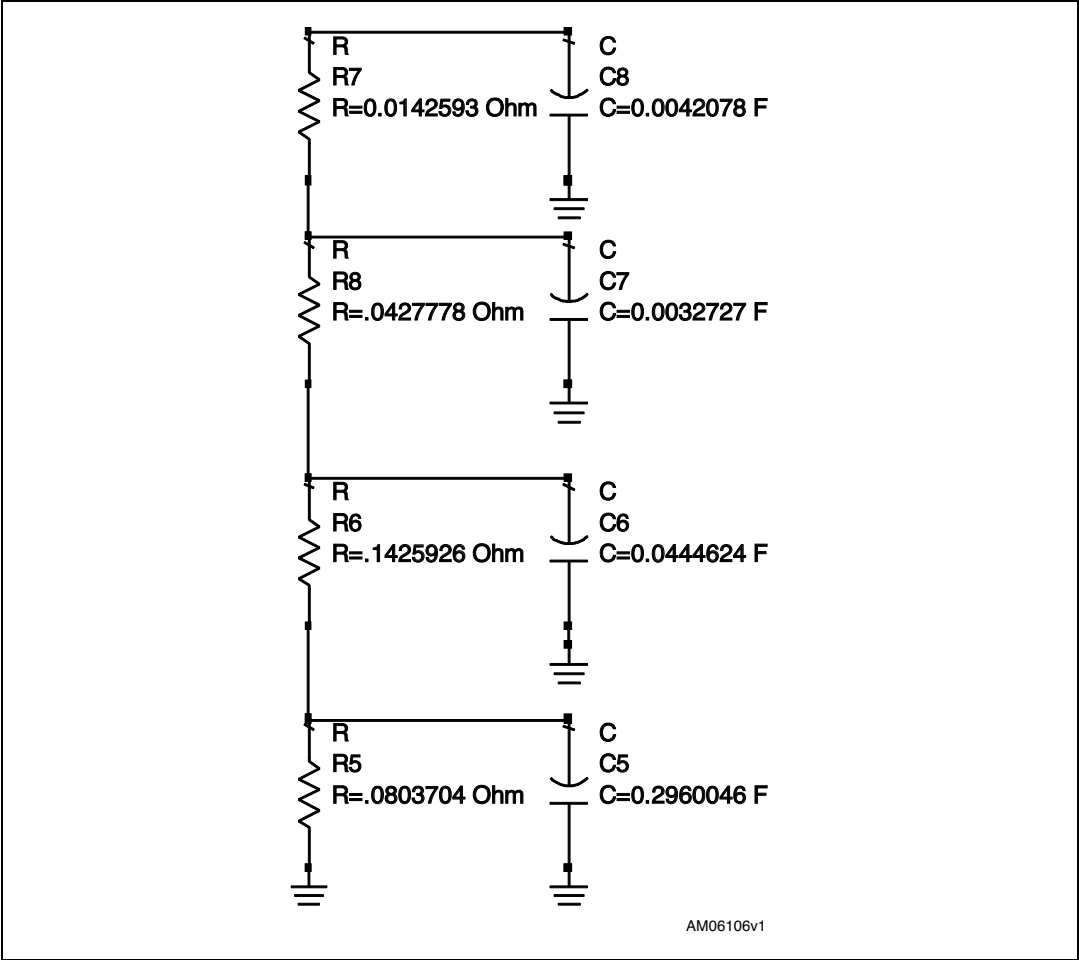


Figure 6. Power gain vs. output power

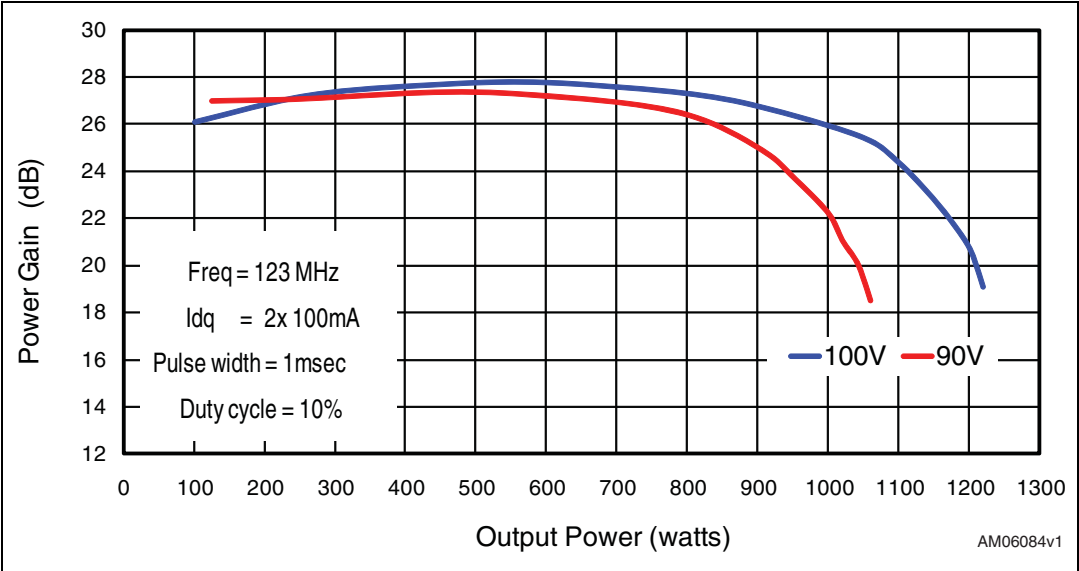
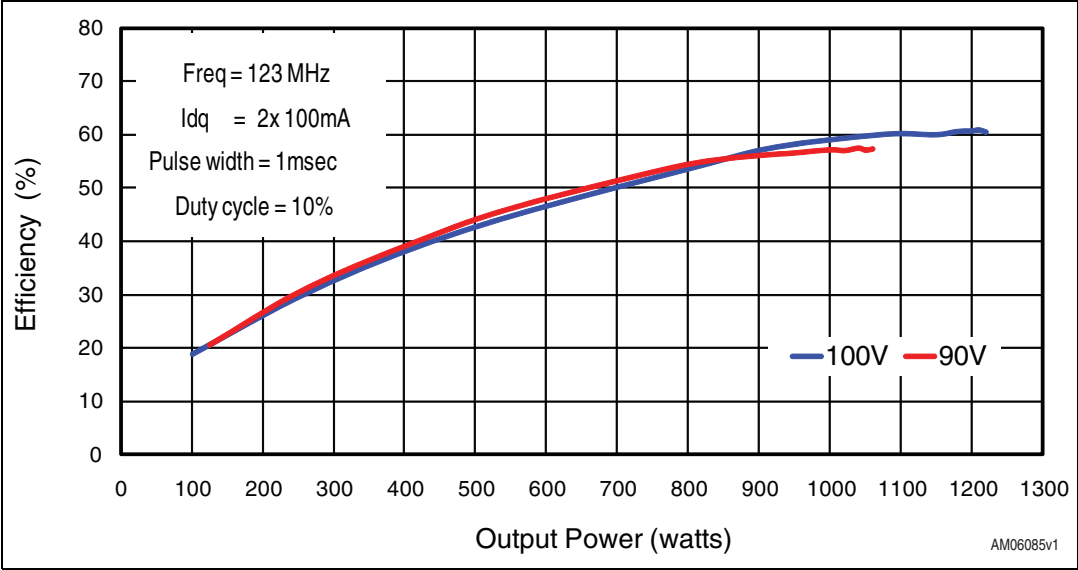


Figure 7. Efficiency vs. output power





## 5 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Table 7. STAC244B mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	5.08		5.59
A1	4.32		4.83
B	4.32		5.33
C	9.65		9.91
D	17.78		18.08
E	33.88		34.19
F	0.10		0.15
G		1.02	
H	1.45		1.70
I	4.83		5.33
J	9.27		9.52
K	27.69		28.19
L	3.12	3.23	3.33
M	3.35	3.45	3.56

Technical drawing of a microelectronic package showing top and side views with dimensions and labels.

**Top View Dimensions and Labels:**

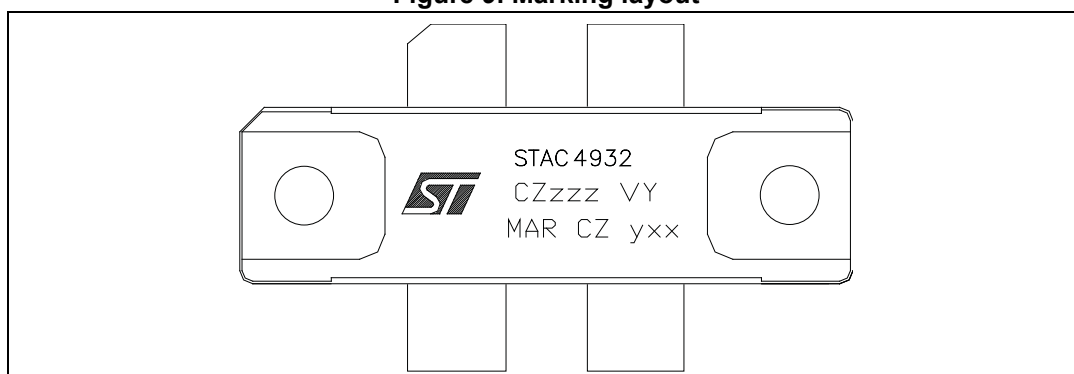
- Lead Dimensions:**
  - Lead 1:  $.100/2,54 \times 45^\circ$
  - Lead 2:  $.060/1,52 \times 45^\circ$
- Mounting Pads:**
  - Pad 1:  $1$
  - Pad 2:  $1$
  - Pad 3:  $3$
  - Pad 4:  $3$
- Pin Dimensions:**
  - Pin 1:  $2XL$
  - Pin 2:  $2XM$
  - Pin 3:  $2XA1$
  - Pin 4:  $4XA$
- Other Dimensions:**
  - Pin 5:  $4XB$
  - Pin 6:  $4XC$
  - Pin 7:  $4XD$
  - Pin 8:  $4XE$
  - Pin 9:  $4XF$
  - Pin 10:  $4XH$
  - Pin 11:  $4XI$
  - Pin 12:  $4XJ$
  - Pin 13:  $4XK$
  - Pin 14:  $4XL$
  - Pin 15:  $4XM$
  - Pin 16:  $4XN$
  - Pin 17:  $4XO$
  - Pin 18:  $4XP$
  - Pin 19:  $4XQ$
  - Pin 20:  $4XR$
  - Pin 21:  $4XS$
  - Pin 22:  $4XT$
  - Pin 23:  $4XU$
  - Pin 24:  $4XV$
  - Pin 25:  $4XW$
  - Pin 26:  $4XX$
  - Pin 27:  $4XY$
  - Pin 28:  $4XZ$
- Other Labels:**
  - $3X R$
  - $.025/0,63$
  - $4X R$
  - $.060/1,52$
  - $2X10^\circ$
  - $SEATING PLANE$
  - $PIN 2$
  - $THERMAL BASE$

## 6 Marking, packing and shipping specifications

**Table 8. Packing and shipping specifications**

Order code	Packaging	Pcs per tray	Dry pack humidity	Lot code
STAC4932B	Tray	20	< 10%	Not mixed

**Figure 9. Marking layout**



**Table 9. Marking specifications**

Symbol	Description
CZ	Assembly plant
zzz	Last 3 digits of diffusion lot
VY	Diffusion plant
MAR	Country of origin
CZ	Test and finishing plant
y	Assembly year
xx	Assembly week

## 7 Revision history

**Table 10. Document revision history**

Date	Revision	Changes
19-Feb-2010	1	First release.
26-May-2010	2	Document status promoted from preliminary data to datasheet.
03-Aug-2010	3	Updated description on cover page and <a href="#">Table 3</a> .
03-Sep-2010	4	Updated figures: <a href="#">3</a> , <a href="#">4</a> and <a href="#">5</a> .
12-Sep-2011	5	Inserted new <a href="#">Section 6: Marking, packing and shipping specifications</a> . Updated <a href="#">Table 6</a> . Minor text changes.
01-Jul-2013	6	Modified pin labeling in <a href="#">Figure 1: Pin connection</a> . Modified document title. Minor text corrections throughout document.

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